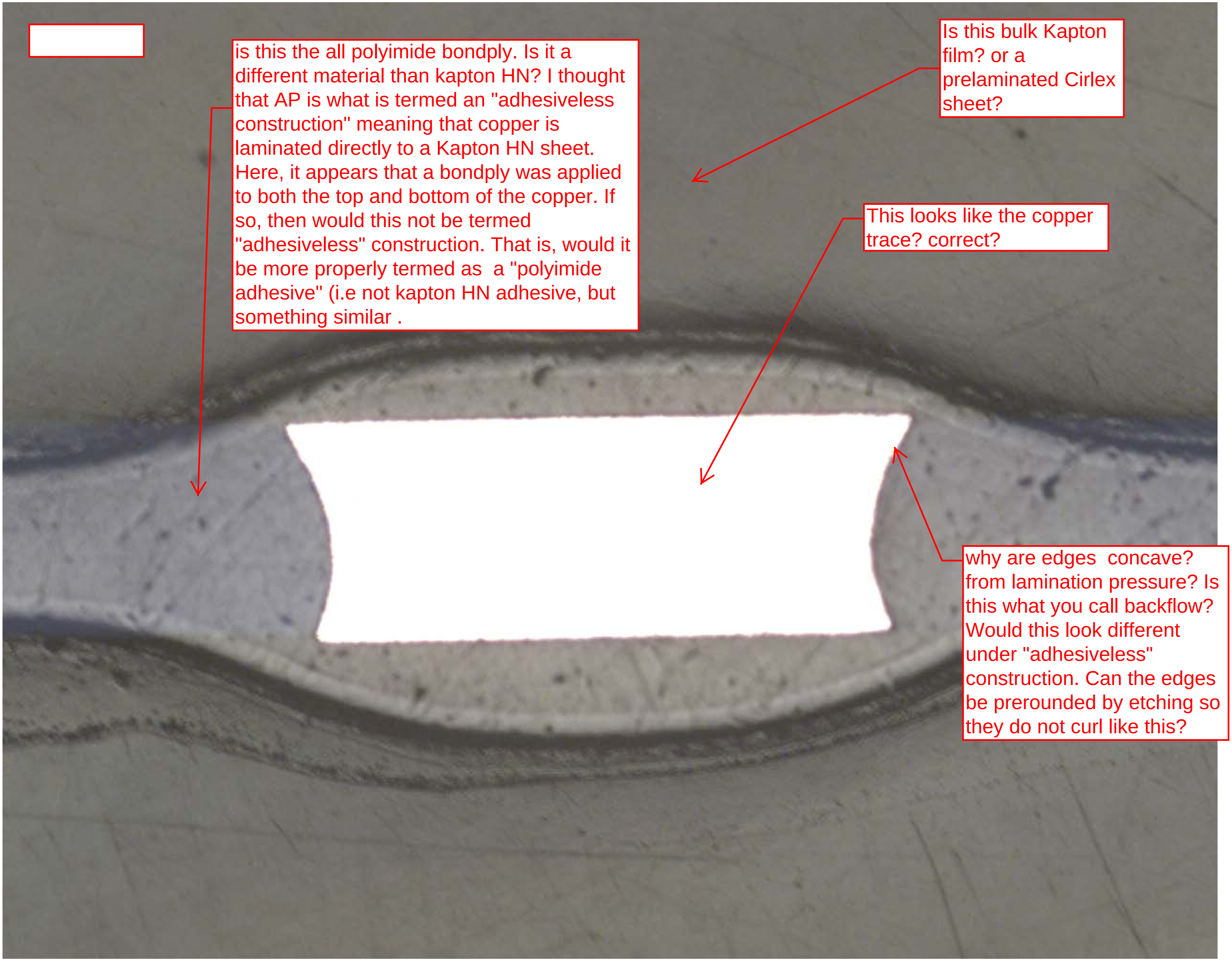

is this the all polyimide bondply. Is it a different material than kapton HN? I thought that AP is what is termed an "adhesiveless construction" meaning that copper is laminated directly to a Kapton HN sheet. Here, it appears that a bondply was applied to both the top and bottom of the copper. If so, then would this not be termed "adhesiveless" construction. That is, would it be more properly termed as  a "polyimide adhesive" (i.e not kapton HN adhesive, but something similar .

Is this bulk Kapton film? or a prelaminated Cirlex sheet?

This looks like the copper trace? correct?

why are edges  concave? from lamination pressure? Is this what you call backflow? Would this look different under "adhesiveless" construction. Can the edges be prerounded by etching so they do not curl like this?